



N 沟道增强型场效应晶体管
N-CHANNEL MOSFET
FHS120N03B/FHD120N03B

主要参数 MAIN CHARACTERISTICS

ID	120 A
VDSS	30 V
Rdson-typ (@Vgs=10V)	3.0 mΩ
Rdson-typ (@Vgs=4.5V)	4.2 mΩ
Qg-typ	48nC

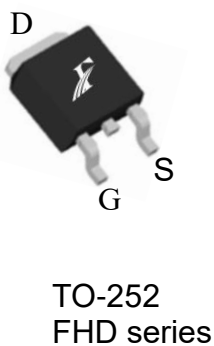
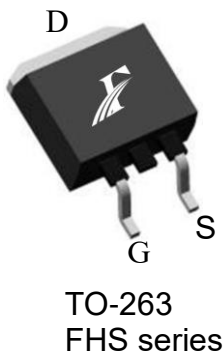
用途 APPLICATIONS

DC-DC转换器和功率开关	DC-DC converter and switch mode power supplies
电池管理系统	BMS

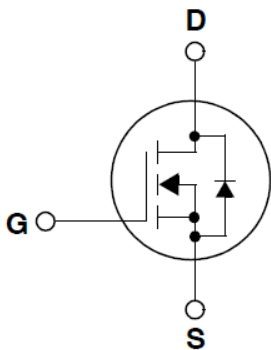
产品特性 FEATURES

低栅极电荷	Low gate charge
低 Crss (典型值 120pF)	Low Crss (typical 120pF)
开关速度快	Fast switching
100%经过 Rg 测试	100% Rg tested
100%经过雪崩测试	100% avalanche tested
100%经过热阻测试	100% DVDS tested
高抗 dv/dt 能力	Improved dv/dt capability
Trench 工艺	Trench process
RoHS 产品	RoHS product

封装形式 Package



等效电路 Equivalent Circuit



绝对最大额定值 ABSOLUTE RATINGS (Tc=25℃)

项目 Parameter	符号 Symbol	数值 Value		单位 Unit
		FHS120N03B	FHD120N03B	
最高漏极—源极直流电压 Drain-Source Voltage	V _{DS}	30		V
连续漏极电流* Drain Current -continuous *	I _D (T _C =25℃), Silicon Limited	120		A
	I _D (T _C =100℃), Silicon Limited	68		
最大脉冲漏极电流（注 1） Drain Current – pulse（note 1）	I _{DM}	480		A
最高栅源电压 Gate-Source Voltage	V _{GS}	±20		V
单脉冲雪崩能量（注 2） Single Pulsed Avalanche Energy（note 2）	E _{AS}	100		mJ
雪崩电流（注 1） Avalanche Current（note 1）	I _{AR}	10		A
重复雪崩能量（注 1） Repetitive Avalanche Current（note 1）	E _{AR}	7		mJ
二极管反向恢复最大电压变化速率（注 3） Peak Diode Recovery dv/dt（note 3）	dv/dt	5.0		V/ns
耗散功率 Power Dissipation	P _D （T _C =25℃）	100	44.6	W
	-Derate above 25℃	0.65	0.36	W/℃
最高结温及存储温度 Operating and Storage Temperature Range	T _J , T _{STG}	-55～+150		℃
引线最高焊接温度 Maximum Lead Temperature for Soldering Purposes	T _L	300		℃

*漏极电流由最高结温限制

*Drain current limited by maximum junction temperature

电特性 ELECTRICAL CHARACTERISTICS

项目 Parameter	符号 Symbol	测试条件 Tests conditions	最小 Min	典型 Typ	最大 Max	单位 Units
关态特性 Off –Characteristics						
漏－源击穿电压 Drain-Source Voltage	BV _{DSS}	I _D =250μA, V _{GS} =0V	30	-	-	V
击穿电压温度特性 Breakdown Voltage Temperature Coefficient	ΔBV _{DSS} /Δ T _J	I _D =250μA, referenced to 25℃	-	0.03	-	V/℃
零栅压下漏极漏电流 Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V, T _C =25℃	-	-	1	μA
		V _{DS} =24V, T _C =125℃	-	-	50	μA
栅极体漏电流 Gate-body leakage current	I _{GSS} (F/R)	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
通态特性 On-Characteristics						
阈值电压 Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.0	1.4	2.0	V
静态导通电阻 Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V , I _D =20A	-	3.0	4.2	mΩ
		V _{GS} =4.5V , I _D =16A	-	4.2	6.0	mΩ
正向跨导 Forward Transconductance	g _{fs}	V _{DS} = 5V, I _D =10A (note 4)	-	47	-	S
动态特性 Dynamic Characteristics						
栅电阻 Gate Resistance	R _g	f=1.0MHz,V _{DS} OPEN	-	1.5	-	Ω
输入电容 Input capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	2450	-	pF
输出电容 Output capacitance	C _{oss}		-	175	-	
反向传输电容 Reverse transfer capacitance	C _{rss}		-	120	-	
开关特性 Switching Characteristics						
延迟时间 Turn-On delay time	t _{d(on)}	V _{DD} =34V, I _D =30A, R _G =4.7Ω V _{GS} =10V (note 4, 5)	-	20	-	ns
上升时间 Turn-On rise time	t _r		-	60	-	ns
延迟时间 Turn-Off delay time	t _{d(off)}		-	59	-	ns
下降时间 Turn-Off Fall time	t _f		-	24	-	ns
栅极电荷总量 Total Gate Charge	Q _g	V _{DS} =15V , I _D =20A , V _{GS} =10V (note 4, 5)	-	48	-	nC
栅－源电荷 Gate-Source charge	Q _{gs}		-	10	-	nC
栅－漏电荷 Gate-Drain charge	Q _{gd}		-	22	-	nC
漏－源二极管特性及最大额定值 Drain-Source Diode Characteristics and Maximum Ratings						
正向最大连续电流 Maximum Continuous Drain -Source Diode Forward Current	I _S		-	-	120	A
正向最大脉冲电流 Maximum Pulsed Drain-Source Diode Forward Current	I _{SM}		-	-	480	A
正向压降 Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =20A	-	0.8	1.4	V
反向恢复时间 Reverse recovery time	t _{rr}	V _{GS} =0V, I _S =20A ,dI _F /dt=100A/μs (note 4)	-	30	-	ns
反向恢复电荷 Reverse recovery charge	Q _{rr}		-	20	-	nC

热特性 THERMAL CHARACTERISTIC

项目 Parameter	符号 Symbol	FHS120N03B	FHD120N03B	单位 Unit
结到管壳的热阻 Thermal Resistance, Junction to Case	Rth(j-c)	1.2	2.1	℃/W
结到环境的热阻 Thermal Resistance, Junction to Ambient	Rth(j-A)	62.5	110	℃/W

注释：
1：脉冲宽度由最高结温限制
2：L=1mH, IAS=10A, VDD=25V, RG=25 Ω,起始结温 TJ=25℃
3：ISD ≤120A,di/dt ≤300A/μs,VDD≤BVDS,起始结温 TJ=25℃
4：脉冲测试：脉冲宽度 ≤300μs,占空比≤2%
5：基本与工作温度无关

Notes:
1: Pulse width limited by maximum junction temperature
2: L=1mH, IAS=10A, VDD=25V, RG=25 Ω,Starting TJ=25℃
3: ISD ≤120A,di/dt ≤300A/μs,VDD≤BVDS, Starting TJ=25℃
4: Pulse Test: Pulse Width ≤300μs,Duty Cycle≤2%
5: Essentially independent of operating temperature

Typical Performance Characteristics

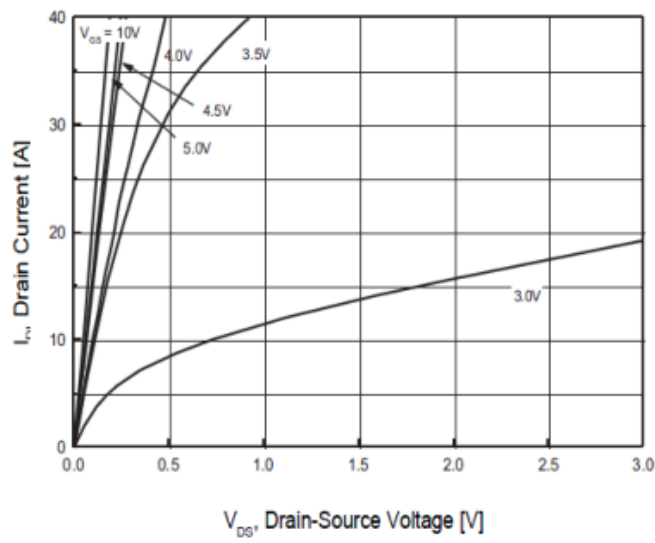


Fig.1 On-Region Characteristics

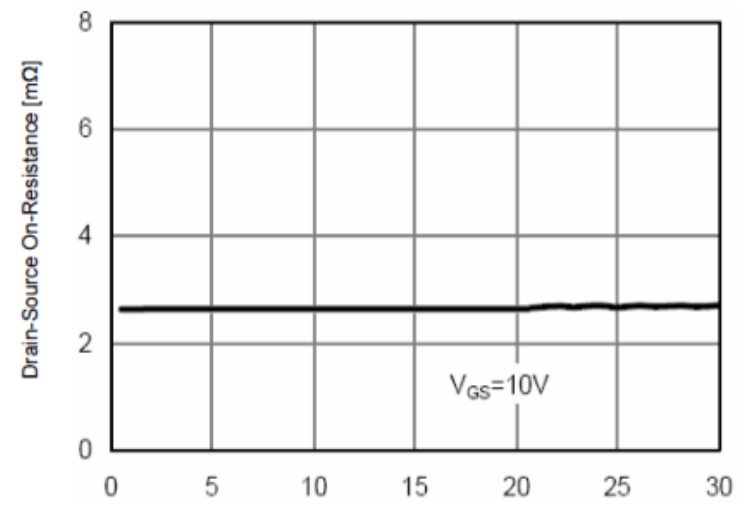


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

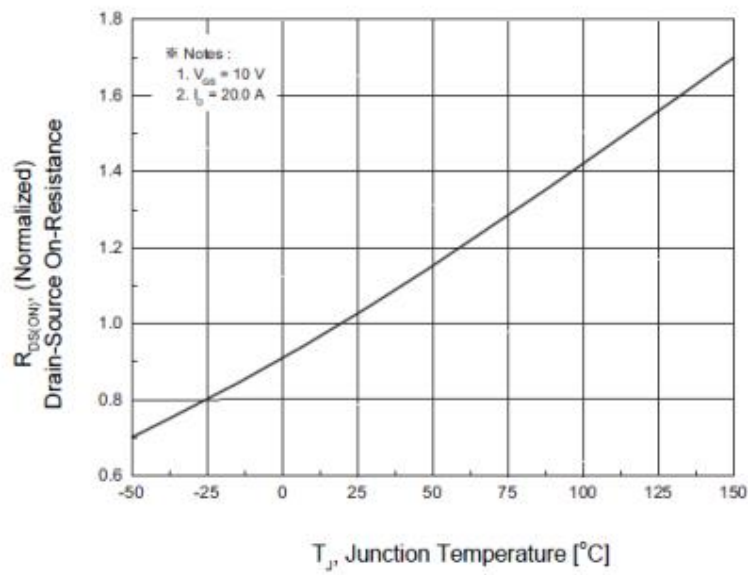


Fig.3 On-Resistance Variation with Temperature

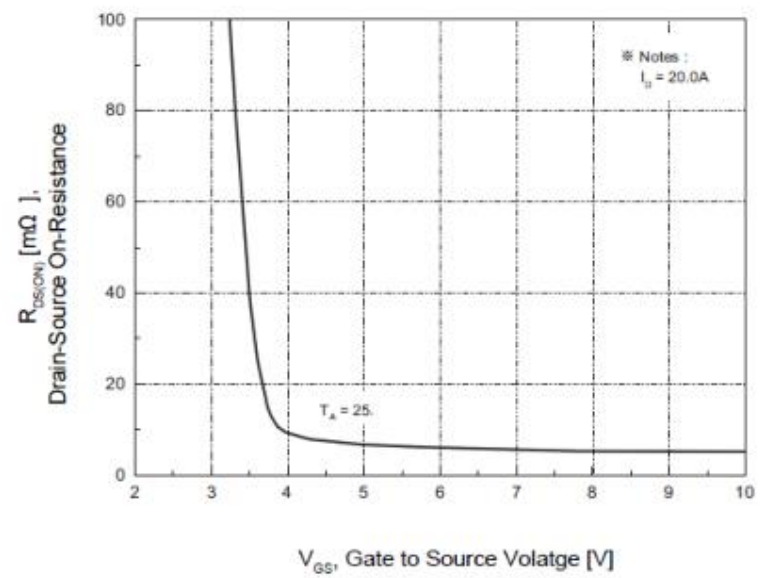


Fig.4 On-Resistance Variation with Gate to Source Voltage

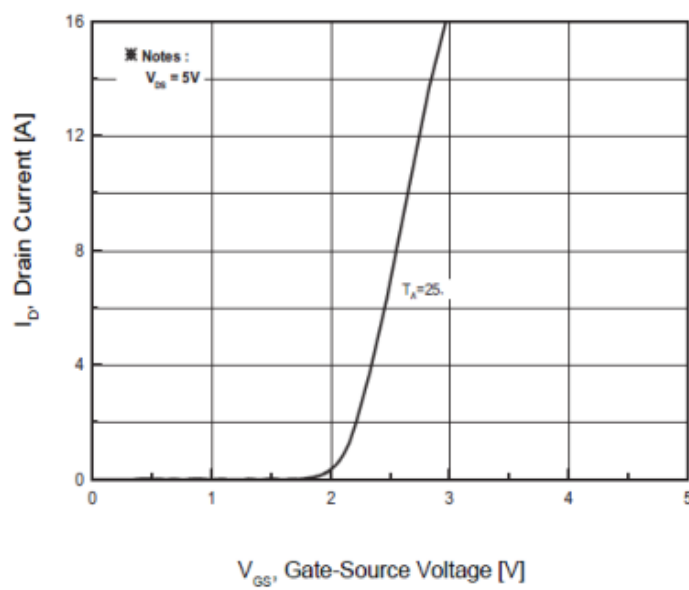


Fig.5 Transfer Characteristics

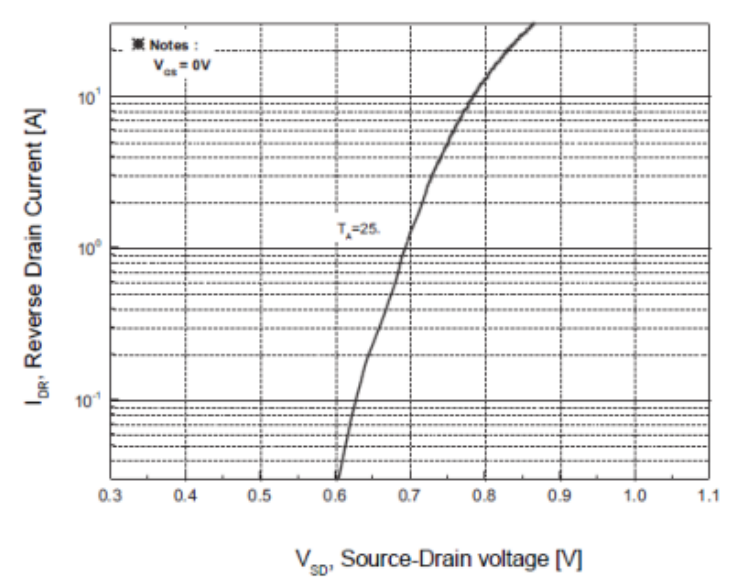
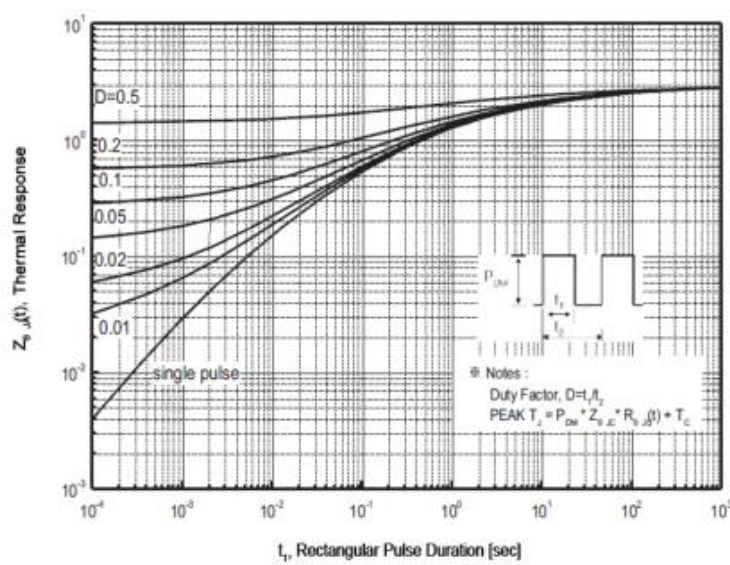
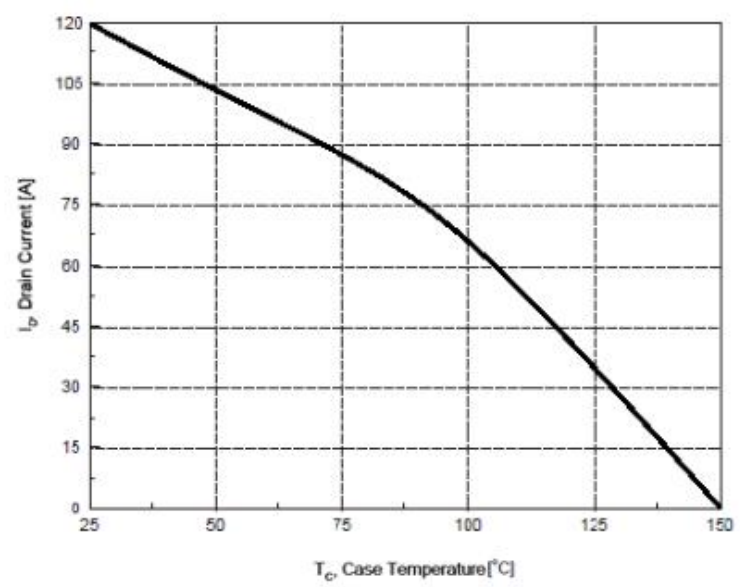
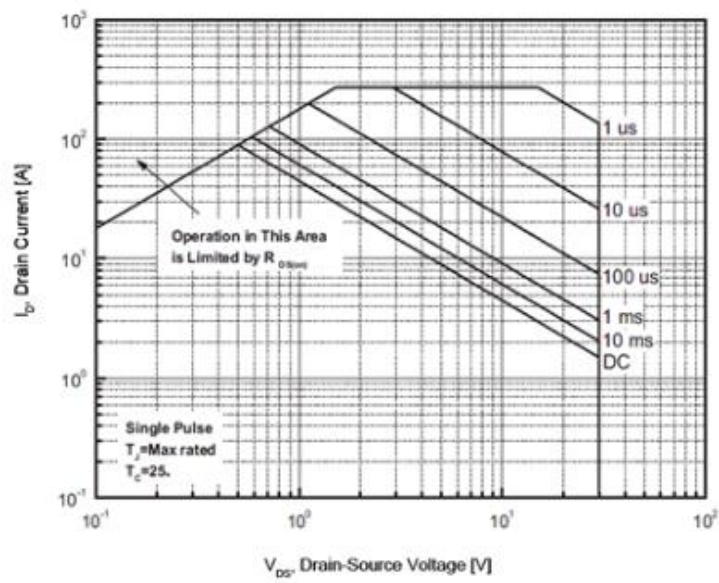
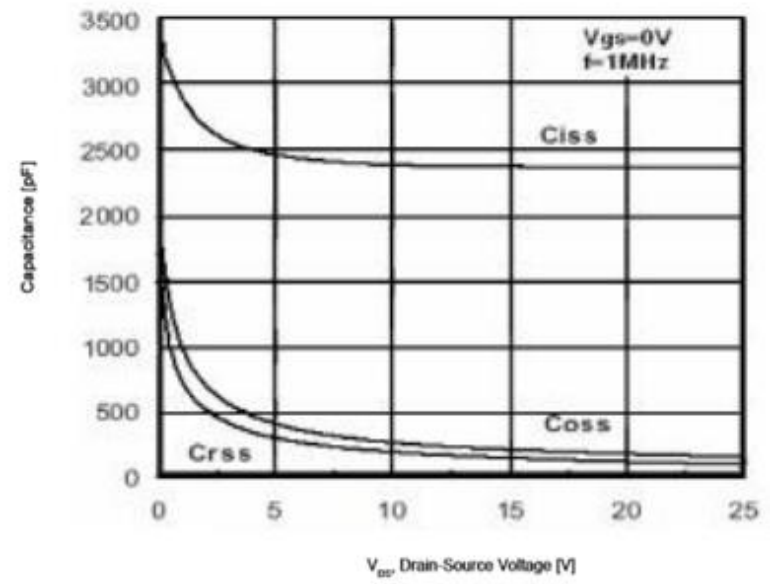
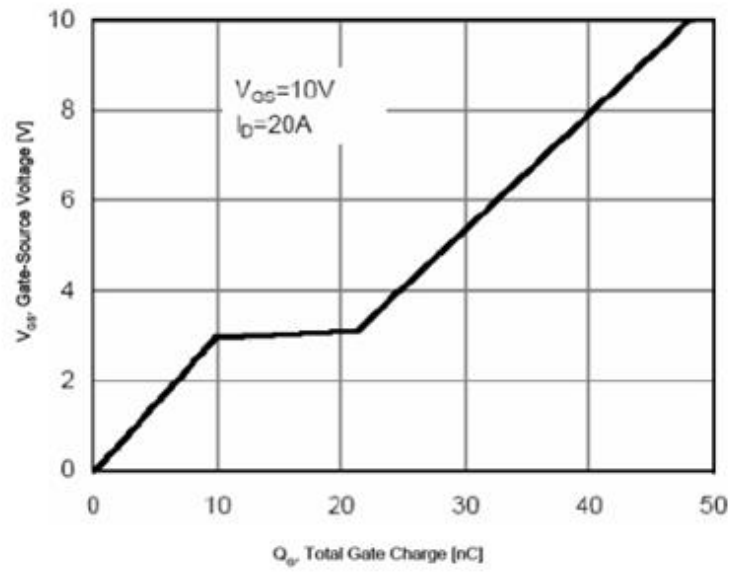
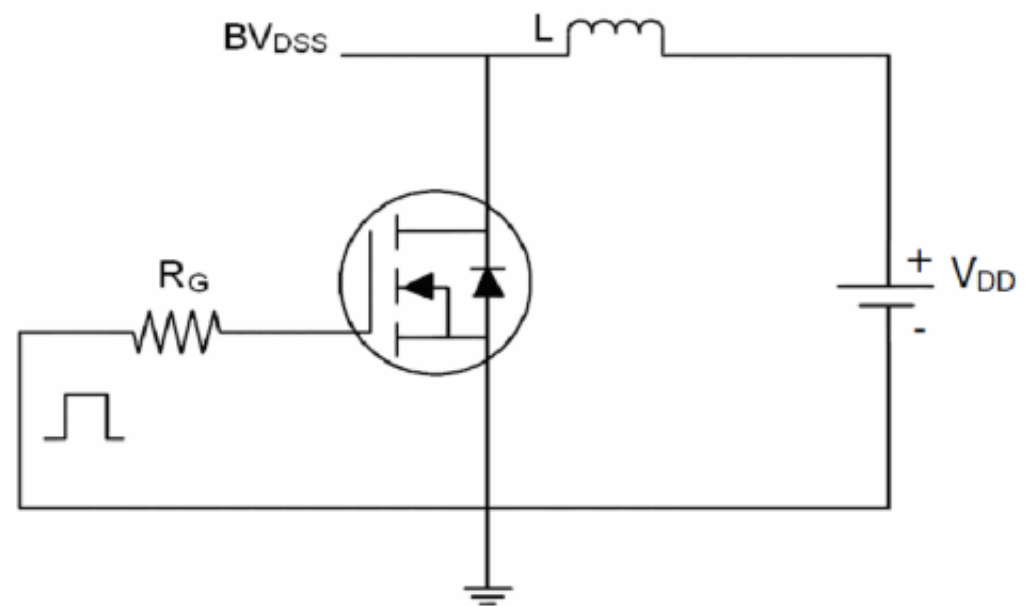


Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature

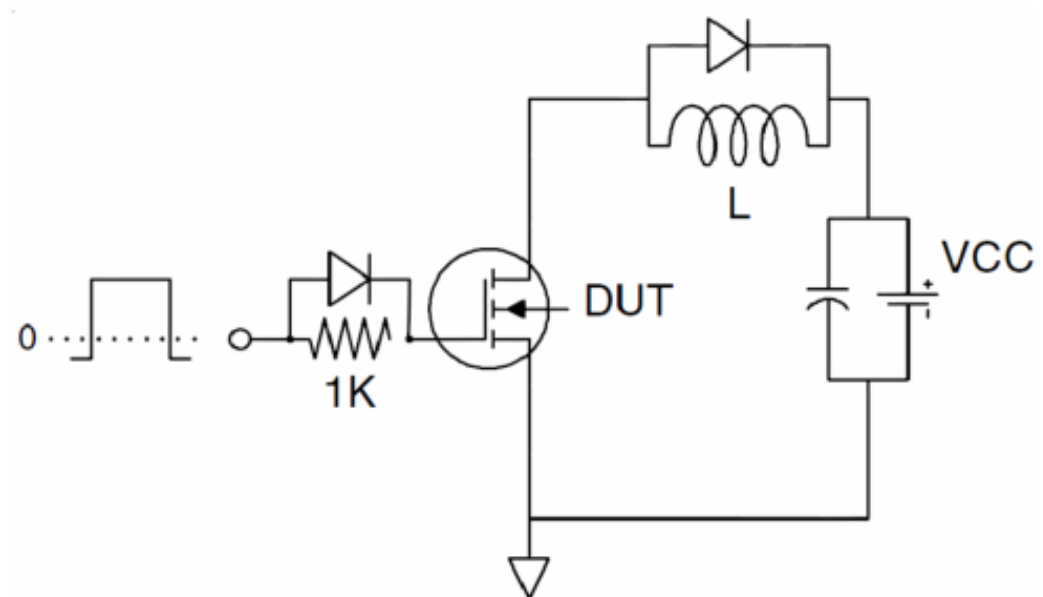


Test Circuit & Waveform

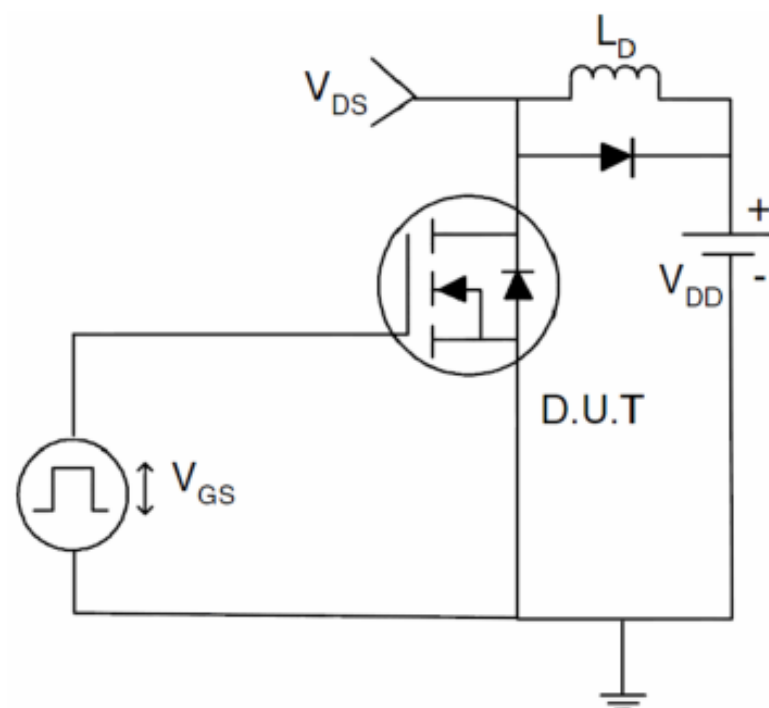
1) E_{AS} test Circuits



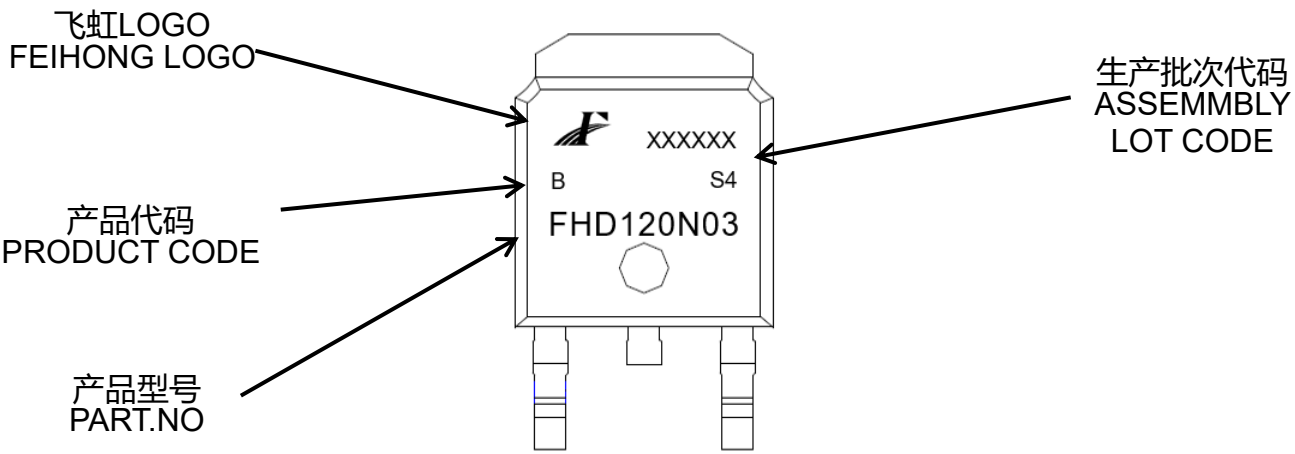
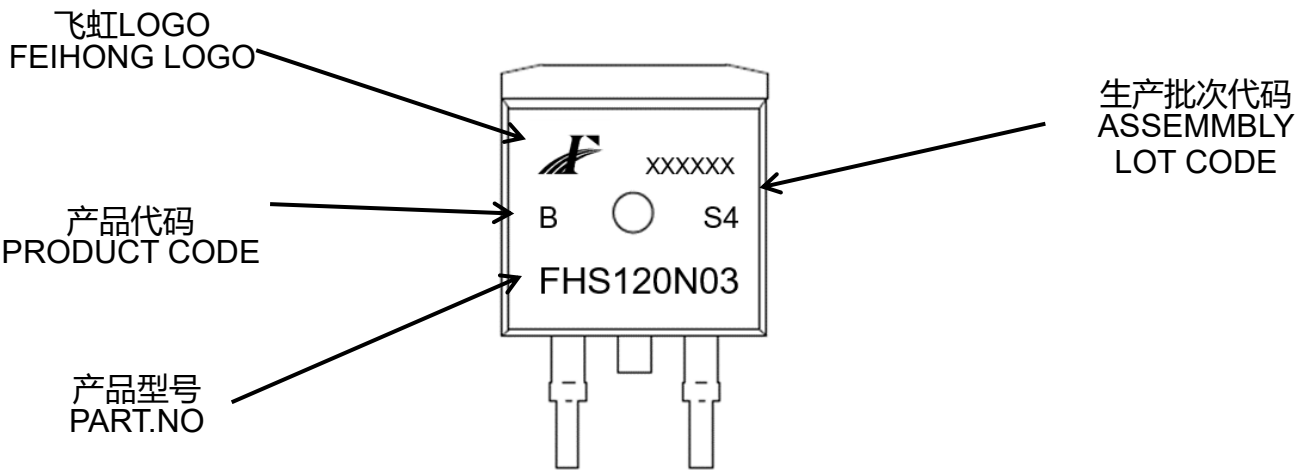
2) Gate charge test Circuit:



3) Switch Time Test Circuit:



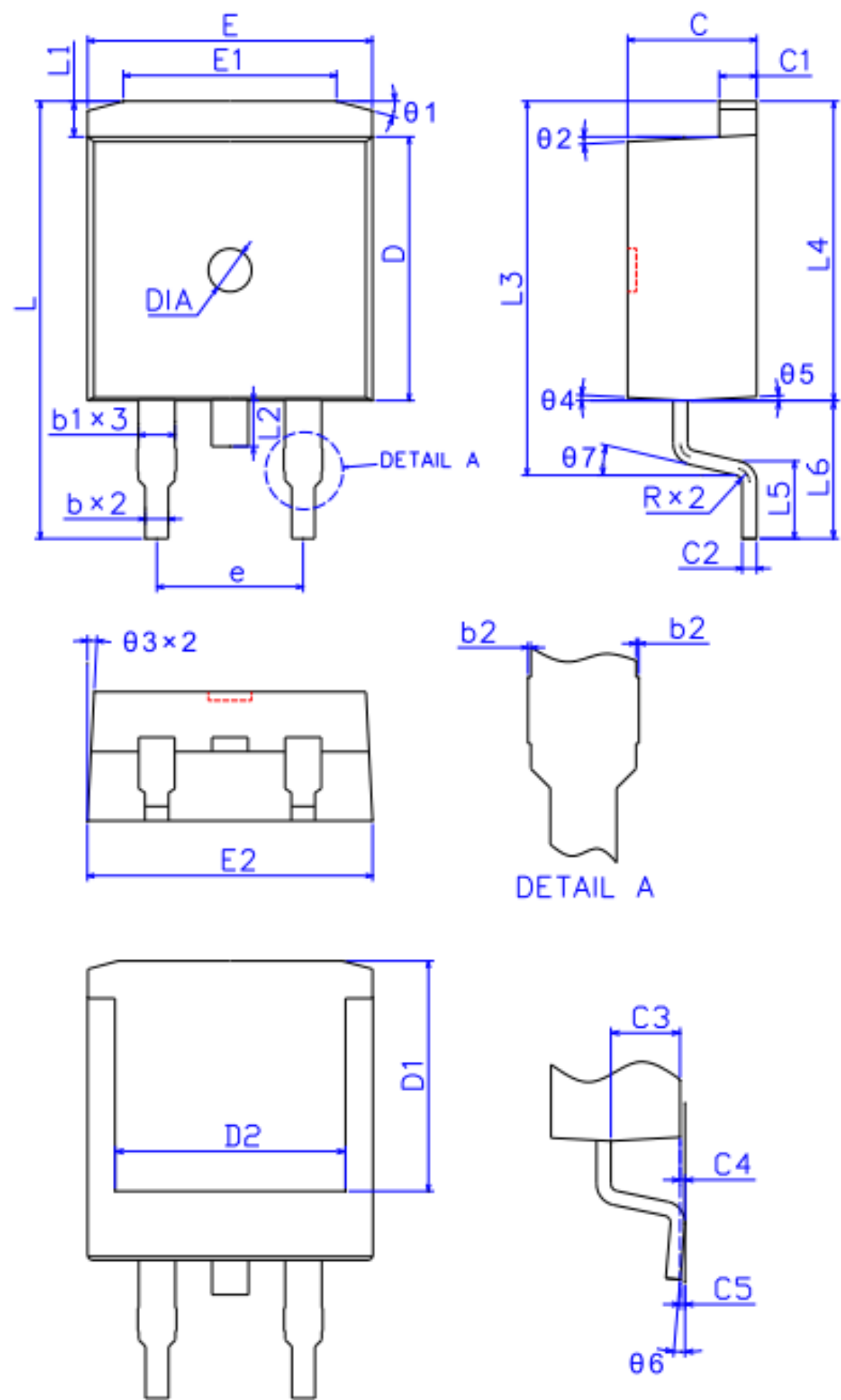
印记 Marking:



外形尺寸:

Package Dimension:

TO-263

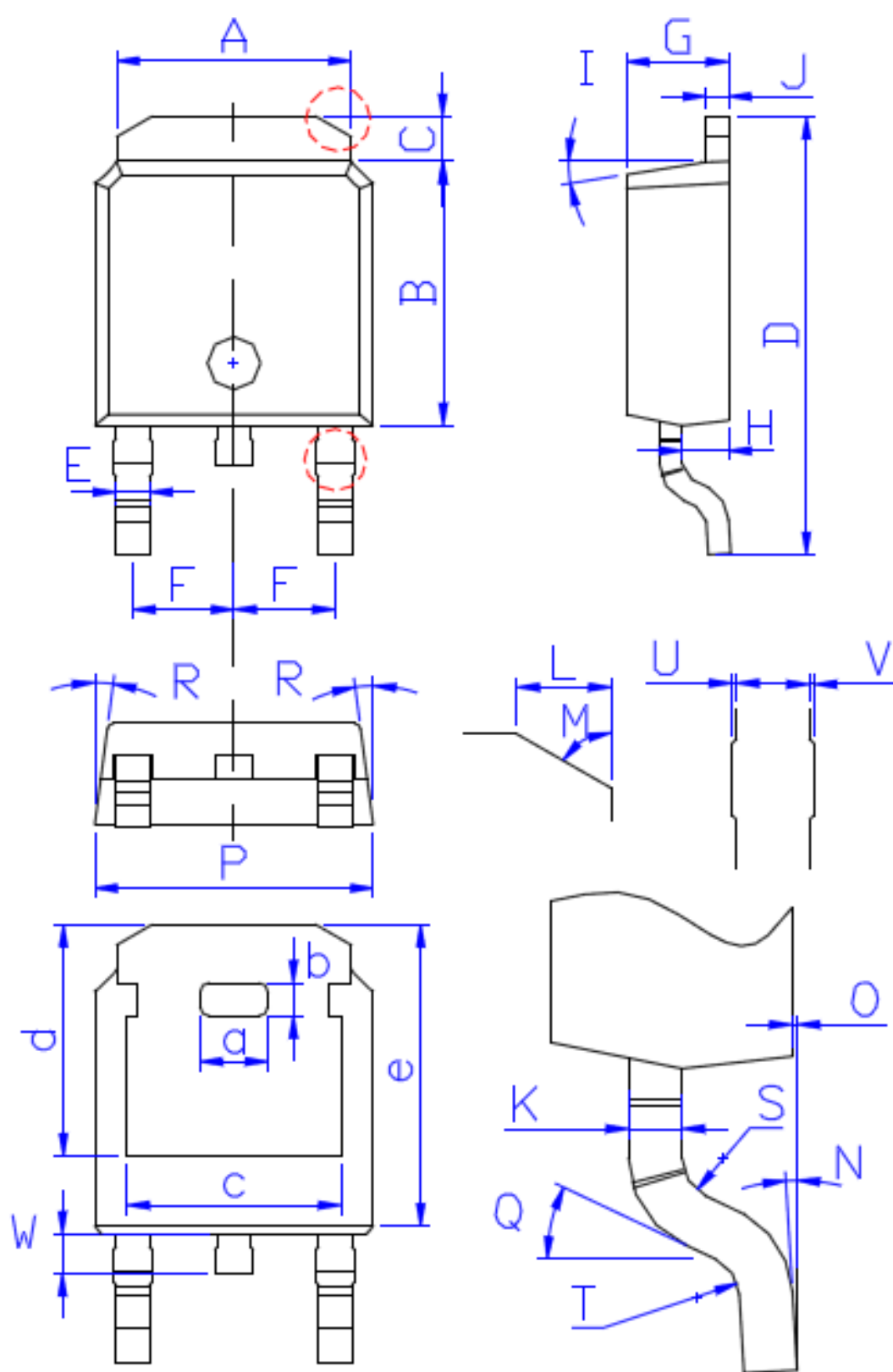


标注	尺寸(mm)
E	9.88±0.10
E1	7.40±0.20
E2	9.90±0.15
L	15.20±0.25
L1	1.30±0.15
L2	1.60±0.10
L3	13.00±0.20
L4	10.40±0.15
L5	2.60±0.15
L6	4.80±0.20
b	0.80±0.07
b1	1.27±0.07
b2	0.05±0.07
C	4.48±0.10
C1	1.30±0.07
C2	0.50±0.07
C3	2.40±0.06
C4	0.10±0.08
C5	0.10±0.08
D	9.20±0.10
D1	8.00±0.10
D2	8.00±0.10
R	0.50±0.10
θ1	15° ±2°
θ2	3° ±2°
θ3	3° ±2°
θ4	3° ±2°
θ5	3° ±2°
θ6	0° ~6°
θ7	13° ±2°
e	5.08±0.10
DIA	宽 1.50±0.10 深 0.30±0.15

外形尺寸:

Package Dimension:

TO-252



DIM	MILLIMETERS
A	5.34 ± 0.30
B	6.00 ± 0.30
C	1.05 ± 0.30
D	9.95 ± 0.30
E	0.76 ± 0.15
F	2.28 ± 0.15
G	2.30 ± 0.30
H	1.06 ± 0.30
I	$(4-10)^{\circ}$
J	0.51 ± 0.15
K	0.52 ± 0.15
L	0.80 ± 0.30
M	60°
N	$(0-10)^{\circ}$
O	0.05 ± 0.05
P	6.60 ± 0.30
Q	25°
R	$(4-8.5)^{\circ}$
S	$R0.40$
T	$R0.40$
U	0.05 ± 0.05
V	0.05 ± 0.05
W	0.90 ± 0.30
a	1.80 ± 0.30
b	0.75 ± 0.30
c	4.85 ± 0.30
d	5.30 ± 0.30
e	6.90 ± 0.30

(Units: mm)